

WHAT IS CLAIMED IS:

1. A thermoplastic resin composition, comprising;
  - (A) 50 to 90 parts by weight of a polyamide,
  - (B) 50 to 10 parts by weight of a polyphenylene ether, and
  - (C) 1 to 35 parts by weight of a block copolymer comprising at least one polymer block mainly composed of an aromatic vinyl compound and at least one polymer block mainly composed of a conjugated diene compound and/or the block copolymer which is hydrogenated, the amount of the component (C) being with respect to 100 parts by weight of the sum of (A) and (B), wherein the component (C) is a mixture of two or more block copolymers comprising (C1) a block copolymer containing a polymer block mainly composed of an aromatic vinyl compound in an amount of 55 weight % or more but less than 90 weight % and (C2) a block copolymer containing a polymer block mainly composed of an aromatic vinyl compound in an amount of 20 weight % or more but less than 55 weight %, and one of the polymer block mainly composed of an aromatic vinyl compound in the mixture has a number average molecular weight of 10,000 or more but less than 30,000 and one of the polymer block mainly composed of a conjugated diene compound in the mixture has a number average molecular weight of 50,000 or more but less than

100,000.

2. The thermoplastic resin composition according to Claim 1, wherein the component (C) is the hydrogenated block copolymer comprising at least two polymer blocks mainly composed of an aromatic vinyl compound and at least one polymer block mainly composed of a conjugated diene compound.

3. The thermoplastic resin composition according to Claim 1, wherein one of the polymer block mainly composed of an aromatic vinyl compound in the mixture of two or more block copolymers of the component (C) has a number average molecular weight of 10,000 or more but less than 25,000 and one of the polymer block mainly composed of a conjugated diene compound in the mixture has a number average molecular weight of 50,000 or more but less than 80,000.

4. The thermoplastic resin composition according to Claim 1, wherein the component (C) is a mixture consisting of the block copolymers having a number average molecular weight of less than 120,000.

5. The thermoplastic resin composition according to Claim 1, wherein the molar ratio of the component (C1) and the component (C2),  $N_{(C1)}/N_{(C2)}$ , is in the range of 0.2 to 1.0.

6. The thermoplastic resin composition according to Claim 1, further comprising a conductive material as a component (D) in an amount of less than 3 parts by weight with respect to 100 parts by weight of the sum

of the components (A)-(C).

7. An injection-molded product, comprising the thermoplastic resin composition according to Claim 1.